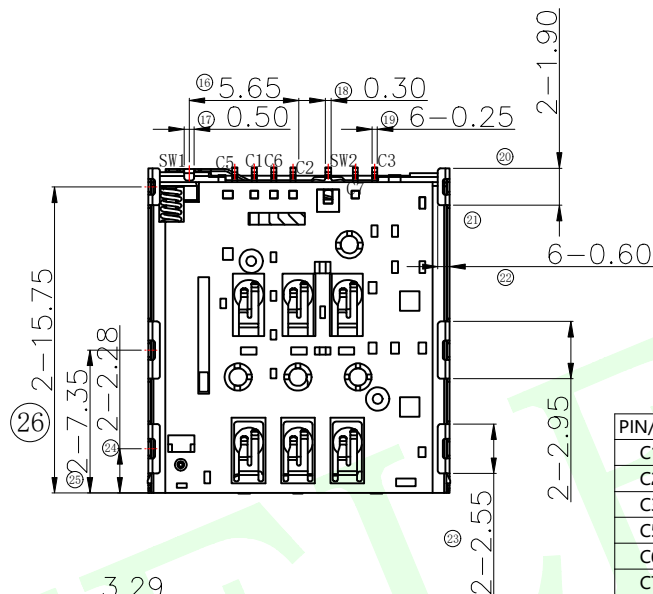
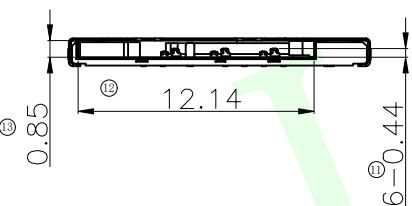
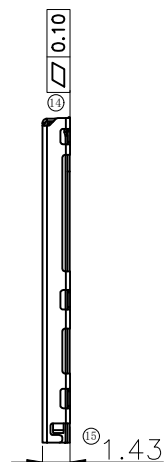


4.00 Card Dashing Position

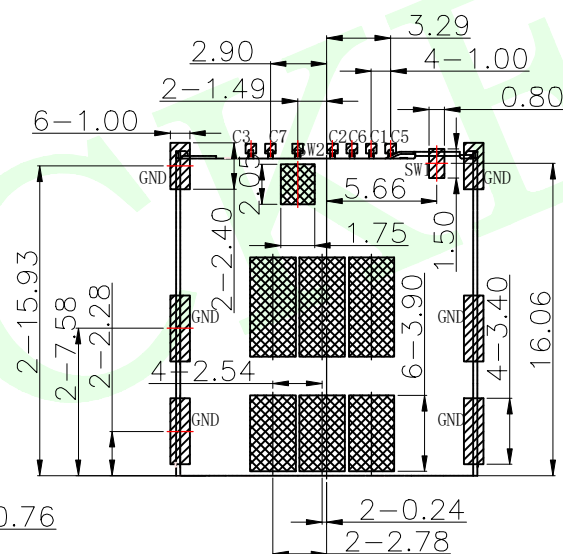
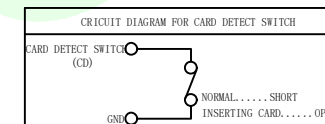


1. Material:
Housing: High Temperature Thermoplastic
Terminal: Copper Alloy
Shell: Stainless Steel

2. Plating:
Terminal: 50u" Ni Underplated Overall
G/F Plated On Contact Area
Tin Plated On Solder Area
Shell: 50u" Ni Underplated Overall
G/F Plated On Contact Area And Older Area

3. Technical Speciality:
Rated Voltage: 30V
Current Rating: 0.5A
Insulation Resistance: 1000MΩ Min.
Contact Resistance: 100mΩ Max.
Withstanding Voltage: 500V DC For 1 Minutes.
Operating Temperature: -40℃ ~ +75℃ Humidity 80% R.H Max.

PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW1	Detect Lever/GND
SW2	Detect Switch

TOLERANCE: ± 0.05

-  SMT SOLDER AREA
 COPPER RESTRICTED AREA
 1. TOUCH AREA OF CONTACT
 TIPS NO ELECTRICAL FUNCTION
 2. NO FIRST PCB_LAYOUT
 CIRCUITS IN THE AREA

连晟欣
LCK
产品类别
MS:MINI SIM
SIM:MICRO SIM
NANO: NANO SIM
流水料号识别码

LCK-SIM-012

P8
产品PIN位
P8: 8PIN

H142
产品高度
H142: L.42MM

W
有柱无柱
Y: 有柱
W: 无柱

L
包装方式
L: 圆盘

G
电镀规格
G: gold flash
G1: 1U
G3: 3U
(以此类推)

 联晟欣连接器（深圳）有限公司
Lianshengxin Connector (Shenzhen) Co., Ltd.

DESIGN	Andy	DATE	2014.12.24	TITLE: MICRO SIM PUSH PUSH 1.42H		
CHECKED		DATE				
APPROVED		DATE				
PART NO: LCK-SIM-012P8H142-WLG				REV: 04	SCALE: 1:1	UNIT: mm
DRAWING NO: 1020221570				SIZE: A4	SHEET: 1/1	